

MCH3376-VB Datasheet

P-Channel 20 V (D-S) MOSFET

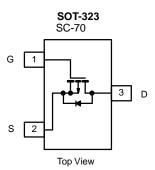
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^c	Q _g (Typ.)			
- 20	0.080 at V _{GS} = - 4.5 V	- 3.1	4.3 nC			
- 20	0.100 at V _{GS} = - 2.5 V	- 2.3	4.0110			

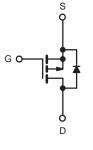
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Load Switch
- DC/DC Converters





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	Γ _A = 25 °C, unless oth	erwise noted)		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 20	V
Gate-Source Voltage		V _{GS}	± 12	v
	T _C = 25 °C		- 3.1	
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C		- 2.1	
Continuous Drain Current (1) = 150°C)	T _A = 25 °C		- 1.4 ^{a, b}	
	T _A = 70 °C	1	- 1.1 ^{a, b}	А
Pulsed Drain Current	I _{DM}	- 6		
Continuous Source-Drain Diode Current	T _C = 25 °C	la la	- 0.4	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 0.3	
	T _C = 25 °C		0.5	
Movimum Douge Dissinction	T _C = 70 °C	P _D	0.3	w
Maximum Power Dissipation	T _A = 25 °C	'D	0.4 ^{a, b}	vv
	T _A = 70 °C		0.3 ^{a, b}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 50 to 150	<u></u>	
Soldering Recommendations (Peak Temperature)		260		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Based on T_C = 25 °C.





Parameter	Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, b}	t ≤ 10 s	R _{thJA}	250	300	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	225	270	C/W	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. Maximum under steady state conditions is 360 °C/W.

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static	Cymbol			199.	max.	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 14		- mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.4		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.45		- 1.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA
	.635	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 2		-	А
	D(01)	V _{GS} = - 4.5 V, I _D = - 1.4 A		0.080		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 1.2 A		0.100		
	03(01)	V _{GS} = - 1.8 V, I _D = - 0.3 A		0.140		
Forward Transconductance ^a	g _{fs}	$V_{DS} = -5 V, I_D = -1.4 A$		5		S
Dynamic ^b	013		L			1
Input Capacitance	C _{iss}			272		pF
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		55		
Reverse Transfer Capacitance	C _{rss}			44		
•		$V_{DS} = -10 \text{ V}, \text{ V}_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -1.4 \text{ A}$		4.3	6.5	1
Total Gate Charge	Qg			2.7	4.1	- nC
Gate-Source Charge	Q _{gs}	V _{DS} = - 10 V, V _{GS} = - 2.5 V, I _D = - 1.4 A		0.7		
Gate-Drain Charge	Q _{ad}			1.0		
Gate Resistance	R _q	f = 1 MHz	1.4	7	14	Ω
Turn-On Delay Time	t _{d(on)}			12	20	
Rise Time	t _r	V _{DD} = - 10 V, R _I = 9.1 Ω		20	30	- ns
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -1.1 \text{ A}, \text{ V}_{\text{GEN}} = -4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		23	35	
Fall Time	t _f			9	18	
Turn-On Delay Time	t _{d(on)}			5	10	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, \text{ R}_{1} = 9.1 \Omega$		10	20	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1.1 A, V_{GEN} = -8 V, R_g = 1 Ω		18	27	
Fall Time	t _f			7	14	
Drain-Source Body Diode Characterist	ics	•		•		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 2.4	
Pulse Diode Forward Current ^a	I _{SM}				- 6	A
Body Diode Voltage	V _{SD}	I _F = - 0.7 A		- 0.8	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			18	27	ns
Body Diode Reverse Recovery Charge	Q _{rr}			7	14	nC
Reverse Recovery Fall Time	t _a	$I_F = -0.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{T}_J = 25 \text{ °C}$		7		ns
Reverse Recovery Rise Time	t _b	1		11		

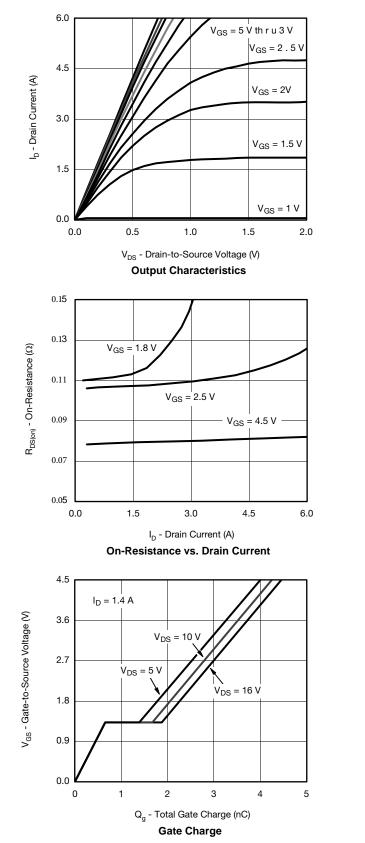
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

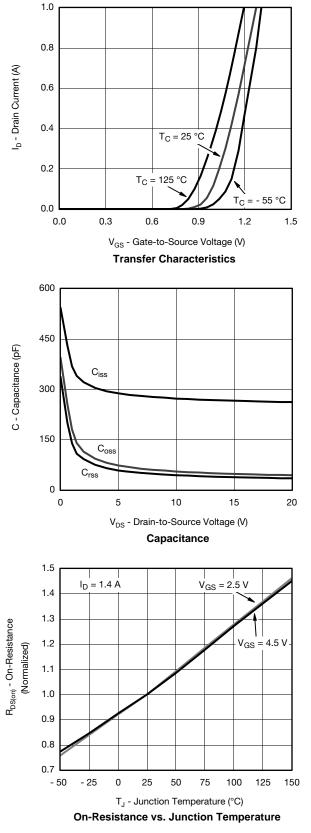
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

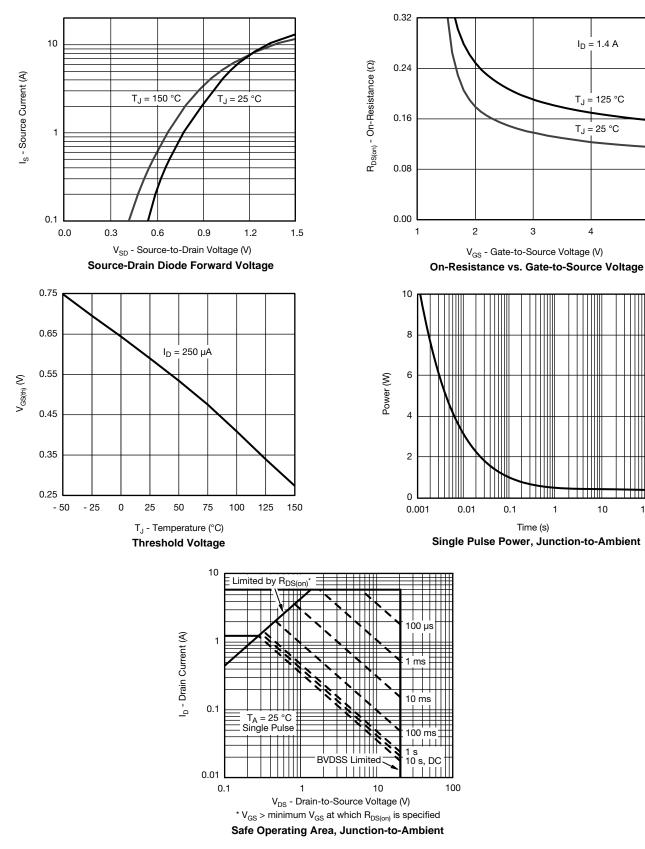


服务热线:400-655-8788



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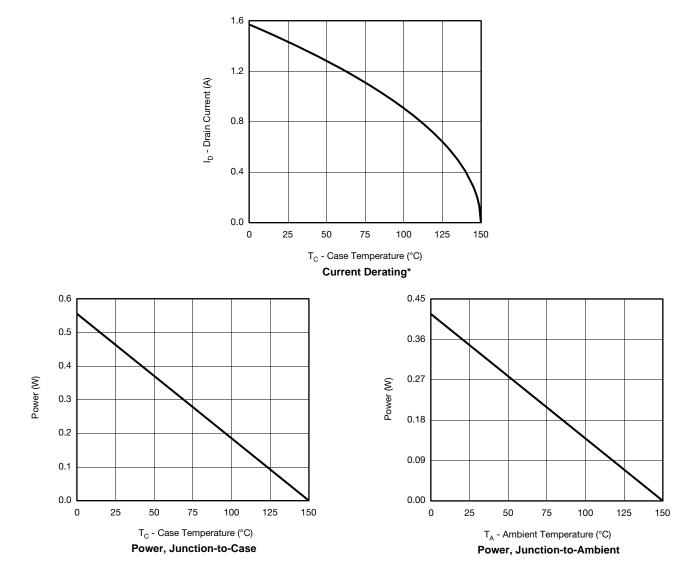
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

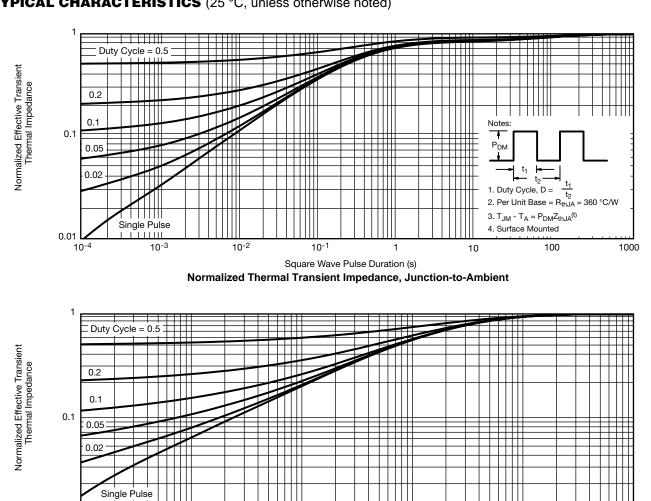


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

0.01 10-4



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

10⁻³

Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Foot

10⁻¹

1

10⁻²

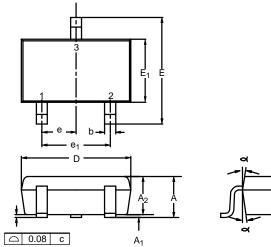
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Bsemi

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SC-70: 3-LEADS

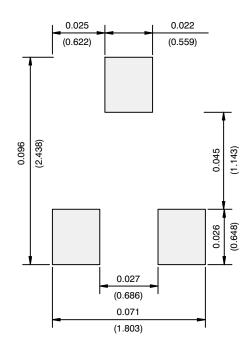


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	MILLIMETERS			INCHES		
Dim	Min	Nom	Max	Min	Nom	Max
Α	0.90	-	1.10	0.035	-	0.043
A ₁	-	-	0.10	-	-	0.004
A ₂	0.80	-	1.00	0.031	-	0.039
b	0.25	-	0.40	0.010	-	0.016
С	0.10	-	0.25	0.004	-	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
Е	1.80	2.10	2.40	0.071	0.083	0.094
E ₁	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65BSC			0.026BSC		
e ₁	1.20	1.30	1.40	0.047	0.051	0.055
L	0.10	0.20	0.30	0.004	0.008	0.012
a	∢ 7°Nom				7°Nom	
ECN: S-03946—Rev. C, 09-Jul-01 DWG: 5549						



RECOMMENDED MINIMUM PADS FOR SC-70: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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